

Amendment under 37 CFR § 1.111  
Serial No. 10/800,630  
Attorney Docket No. 042236

## REMARKS

### Rejections under 35 USC §102(b)

**Claims 5-20 were rejected under 35 USC §102(b) as being anticipated by Farnworth et al (U.S. Patent No. 6,057,597).**

Claims 5, 13 and 14 have been amended to recite, among other things, “wherein the semiconductor device protection has a structure to be detachably attached to the semiconductor device”.

Farnworth et al discloses a semiconductor package with prefabricated cover. The Examiner alleged regarding claim 6 “the semiconductor device protection cover wherein the semiconductor device protection cover has a structure able to be detachably attached to the semiconductor device (col. 3, lines 63-67).” Farnworth et al describes at the cited portion as follows:

Referring again to FIG. 2, the package 10 also includes a protective cover 20. The cover 20 comprises a separate prefabricated member attached to the substrate 10. In addition, the cover 20 encloses the die 12 without being in physical contact therewith, to form an enclosed space bounded by the cover 20 and the substrate 14.

Nothing here indicates that the semiconductor device protection cover has a structure able to be detachably attached to the semiconductor device. Farnworth et al rather describes as follows:

Amendment under 37 CFR § 1.111  
Serial No. 10/800,630  
Attorney Docket No. 042236

Referring again to FIG. 2, the package 10 also includes a seal 28. **The seal 28 secures the cover 20 to the substrate 14**, and forms an air-tight, hermetic seal for the space encompassed by the cover 20. The seal 28 protects and seals the die from contaminants such as particles and gases. Preferably the seal 28 comprises a curable elastomer, such as a silicone adhesive, or a room temperature vulcanizing material. . . . .

The seal 28 can also comprise a relatively incompressible material such as a thermosetting resin or an instant curing elastomer. . . . .

(Col. 4, lines 33-52). Thus, in Farnworth et al, the cover is fixed by adhesive. Farnworth et al does not teach or suggest “wherein the semiconductor device protection has a structure to be detachably attached to the semiconductor device,” as recited in claims 5, 13 and 14.

For at least these reasons, claims 5, 13 and 14 patentably distinguish over Farnworth et al. Claims 6-12 depending from claim 5, claims 15-20 depending from claim 14 also patentably distinguish over Farnworth et al, for at least the same reasons.

#### **Rejections under 35 USC §103(a)**

**Claims 7 and 8 are rejected under 35 USC §103(a) as being obvious over Farnworth et al in view of the remark.**

As discussed above, claims 7 and 8 patentably distinguish over Farnworth et al.

**Claims 15-20 are rejected under 35 USC §103(a) as being obvious over Farnworth et al in view of Fukasawa et al (U.S. Patent No. 6,784,542).**

Amendment under 37 CFR § 1.111  
Serial No. 10/800,630  
Attorney Docket No. 042236

As discussed above, claim 15-20 patentably distinguish over Farnworth et al. Fukasawa et al is cited for allegedly disclosing that the semiconductor device has a first positioning member, and that the semiconductor device protection cover has a second positioning member. Such disclosure, however, does not remedy the deficiencies of Farnworth et al.

For at least these reasons, claim 15-20 patentably distinguish over Farnworth et al.

In view of the aforementioned amendments and accompanying remarks, Applicants submit that that the claims, as herein amended, are in condition for allowance. Applicants request such action at an early date.

If the Examiner believes that this application is not now in condition for allowance, the Examiner is requested to contact Applicants' undersigned attorney to arrange for an interview to expedite the disposition of this case.

If this paper is not timely filed, Applicants respectfully petition for an appropriate extension of time. The fees for such an extension or any other fees that may be due with respect to this paper may be charged to Deposit Account No. 50-2866.

Respectfully submitted,

**WESTERMAN, HATTORI, DANIELS & ADRIAN, LLP**



Sadao Kinashi

Attorney for Applicants

Registration No. 48,075

Telephone: (202) 822-1100

Facsimile: (202) 822-1111

SK/sg

Q:\2004\042236\042236 amd 1.doc